

Title (en)

METHOD FOR CONNECTING A MICROCIRCUIT TO THE INDUCTIVE COUPLING COIL OF A SMART CARD AND ASSEMBLY FOR AN INDUCTIVELY COUPLED SMART CARD

Title (de)

VERFAHREN ZUM ANSCHLUSS EINER MIKROSCHALTUNG AN DIE INDUKTIVE KOPPELSPULE EINER CHIPKARTE UND ANORDNUNG FÜR EINE INDUKTIV GEKOPPELTE CHIPKARTE

Title (fr)

PROCEDE DE RACCORDEMENT D'UN CIRCUIT INTEGRE A LA BOBINE DE COUPLAGE PAR INDUCTION D'UNE CARTE A MEMOIRE, ET ENSEMBLE POUR CARTE A MEMOIRE A COUPLAGE PAR INDUCTION

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Application

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Abstract (en)

[origin: WO9320537A1] The invention concerns a method for connecting a microcircuit (2) to the inductive coupling coil (1, 11) of a smart card and an assembly in an inductively coupled smart card. In accordance with the method according to the invention, during the manufacturing phase of said coil (1), the coil is complemented with a socket (3) incorporating an open recess/slot arrangement (15, 13) to which socket the conductor ends (4, 7) of the coil (1, 11) are attached so as to make them pass over the open recess/slot arrangement (13, 15) of the socket, and the microcircuit (2) is bonded by its contact areas (5) to the sections of the coil conductors (4, 7) passing over the open recess/slot arrangement (13, 15).

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